



Material Content Data Sheet



Sales Product Name		TLE4729G		Issued		2. August 2018		
MA#		MA000768416						
Package		PG-DSO-24-16		Weight*		717.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.582	2.45	2.45	24501	24501
leadframe	inorganic material	phosphorus	7723-14-0	0.050	0.01		70	
	non noble metal	zinc	7440-66-6	0.202	0.03		281	
	non noble metal	iron	7439-89-6	4.030	0.56		5616	
wire	non noble metal	copper	7440-50-8	163.640	22.80	23.40	228039	234006
	noble metal	gold	7440-57-5	0.494	0.07	0.07	688	688
	encapsulation	organic material	carbon black	1333-86-4	1.046	0.15		1457
encapsulation	plastics	epoxy resin	-	48.111	6.70		67044	
	inorganic material	silicondioxide	60676-86-0	473.785	66.02	72.87	660237	728738
leadfinish	non noble metal	tin	7440-31-5	3.194	0.45	0.45	4451	4451
plating	noble metal	silver	7440-22-4	1.086	0.15	0.15	1513	1513
glue	plastics	epoxy resin	-	1.095	0.15		1526	
	noble metal	silver	7440-22-4	3.284	0.46	0.61	4577	6103
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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